



## A unified model for Digitized Heat Transfer in a microchannel



Peter Zhang<sup>a,1</sup>, Kamran Mohseni<sup>a,b,\*</sup>

<sup>a</sup> Department of Mechanical and Aerospace Engineering, University of Florida, 1064 Center Dr. Rm 150, Gainesville, FL 32611, United States

<sup>b</sup> Department of Electrical and Computer Engineering, University of Florida, 1064 Center Dr. Rm 150, Gainesville, FL 32611, United States

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### ABSTRACT

Digitized Heat Transfer (DHT) is a novel method of adaptive thermal management for high powered devices that uses discrete microdroplets to remove heat. In this paper, the heat transfer characteristics of DHT are investigated for parallel plate and axisymmetric circular microchannels using scale analysis and numerical simulations. DHT in axisymmetric microchannels are also studied using experimental tests. Through scale analysis, it is found that DHT is quantified by the Nusselt number ( $Nu$ ) and is a function of the Reynolds number ( $Re$ ), Prandtl number ( $Pr$ ), nondimensional axial distance ( $x/D_H$ ), and droplet aspect ratio ( $\mathcal{R}$ ). In simulation and experiment,  $Nu$  shows a direct relationship with  $Re$  and  $Pr$  as well as an inverse relationship with  $\mathcal{R}$ . Using the Graetz problem as a model, new scaling relations are proposed for the axial distance,  $x$ , and  $Nu$  in an effort to collapse the  $Nu$  curves that exist for different flow parameters. To align the characteristic oscillations of  $Nu$  found in DHT,  $x$  is scaled by the droplet circulation length,  $L_{\text{circ}}$ , to create a new nondimensional axial distance,  $x_{\text{circ}} = \frac{x}{L_{\text{circ}}}$ . In order to match the overall magnitude,  $Nu$  scaling is derived based on the two different modes of heat transfer that occur before and after one circulation length. Prior to one circulation length, heat transfer is characterized by thermal boundary layer growth and the scaling parameter is determined to be  $f_1 = \sqrt{\frac{RePr}{\mathcal{R}}}$ . After one circulation length, recirculation of heat is dominant and a scaling parameter  $f_2$  is found to be a linear function of  $1/\mathcal{R}$ .  $f_2$  is modeled by the equation  $f_2 = \frac{c_1}{\mathcal{R}} + c_2$  where  $c_1$  and  $c_2$  are dependent on  $Re$  and  $Pr$ . The two scaling constants are merged using an inverse tangent weighting function ( $w$ ) so that a fully scaled Nusselt number,  $Nu^*$ , is defined by  $Nu^* = [Nu((1/f_1)(1-w) - (1/f_2)w)]$ . Using this unified model, numerical and experimental data are reduced to a single curve that depicts the heat transfer to any digitized flow. In the future, this model will be helpful in comparing various DHT systems as well as enabling the design of powerful and efficient DHT based thermal management systems.

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### 1. Introduction

One of the largest challenges facing current and future electronic devices is adequate thermal management. Improper cooling of devices results in high temperatures that can reduce performance, decrease life spans, or even cause catastrophic failure. This problem has only been exacerbated as devices have become smaller and more powerful. Already, high performance devices are producing heat fluxes on the order of  $10^3 \text{ W/cm}^2$  [1,2] and are expected to increase to rates greater than  $2500 \text{ W/cm}^2$  [3]. In

comparison, traditional forms of cooling such as air based forced convection is only capable of heat removal on the order of  $10^{-1} \text{ W/cm}^2$ . Clearly, traditional forms are insufficient for state-of-the-art systems, however they are also rapidly becoming insufficient for basic personal computer demands as well. To address the growing demands, engineers have turned to liquid based cooling with various implementation schemes that are capable of significantly higher heat transfer rates.

Some of the liquid cooling schemes that have been previously studied include microjet devices [4], thermionic cooling [5,6], thermoelectric microcoolers [7], and microchannel cooling [8]. Each of these methods have unique advantages and disadvantages, but they all seek a balance between performance, cost, and reliability. While some of these methods have achieved extremely high heat transfer rates, they sacrifice cost and reliability. For example, Silverman et al. reported  $2000 \text{ W/cm}^2$  in microjet devices using liquid metals [9] and Hirshfeld et al. reported  $1500 \text{ W/cm}^2$  in

\* Corresponding author at: Department of Mechanical and Aerospace Engineering, University of Florida, 1064 Center Dr. Rm 150, Gainesville, FL 32611, United States. Tel.: +1 (352) 273 1824.

E-mail addresses: [peter.zhang@ufl.edu](mailto:peter.zhang@ufl.edu) (P. Zhang), [mohseni@ufl.edu](mailto:mohseni@ufl.edu) (K. Mohseni).  
URL: <http://enstrophy.mae.ufl.edu/> (K. Mohseni).

<sup>1</sup> Tel.: +1 (303) 895 5698.

## Nomenclature

$A$	liquid A	$Re_L$	Reynolds number with $L$ as the characteristic length
$a$	sharpness of weighting function	$t$	time
$\mathcal{R}$	droplet aspect ratio	$T$	temperature
$B$	liquid B	$T_w$	temperature at inner wall of channel
$b$	location of transition in weighting function	$T_b$	droplet bulk temperature
$c_p$	specific heat	$T_0$	inlet temperature
$c_1$	coefficient of $f_2$ scaling function	$u$	velocity component parallel to the $x$ -axis
$c_2$	coefficient of $f_2$ scaling function	$U$	bulk velocity along the $x$ -axis
$D$	diameter of axisymmetric channel	$\mathbf{v}$	velocity vector
$D_H$	hydraulic diameter	$w$	scaling weight function
$DHT$	Digitized Heat Transfer	$x$	axis parallel to the line of symmetry in a fixed reference frame
$EWOD$	Electrowetting On a Dielectric	$x'$	axis parallel to the line of symmetry in a moving reference frame
$\mathbf{f}$	body force	$x_{circ}$	axial distance nondimensionalized by circulation length
$f_1$	$Nu$ scaling constant for $x_{circ} < 1$	$x^*$	Graetz number
$f_2$	$Nu$ scaling constant for $x_{circ} > 1$	$X_T$	length along $x$ which a flow becomes thermally fully developed
$h$	heat transfer coefficient	$y$	axis normal to the wall in a parallel plate channel
$H$	height of parallel plate channel	$\alpha$	thermal diffusivity
$k$	thermal conductivity	$\delta_s$	dirac delta function
$L$	length along $x$ -axis	$\delta_T$	thermal boundary layer thickness
$L_A$	length of a droplet of fluid A	$\kappa$	curvature of the interface
$L_B$	length of a droplet of fluid B	$\lambda$	length of droplet fluid A and B combined
$L_D$	length of a droplet	$\mu$	dynamic viscosity
$N_\Gamma$	ratio of diffusion time scale to convection time scale	$\rho$	density
$Nu$	Nusselt number	$\sigma$	surface tension
$Nu^*$	scaled Nusselt number	$\tau_{diff}$	diffusion time scale
$Nu_{avg}$	time averaged $Nu$	$\tau_{circ}$	recirculation time scale
$Nu_{Graetz}$	$Nu$ curve for the Graetz problem	$\theta$	nondimensional temperature
$n$	liquid fraction	$\theta_w$	nondimensional wall temperature
$p$	pressure	$\theta_{avg}$	average nondimensional temperature
$Pe$	Peclet number		
$Pr$	Prandtl number		
$q''$	heat flux		
$r$	axis in radial direction		
$Re$	Reynolds number with $D_H$ as the characteristic length		

microchannels [10]. While effective for high heat flux cooling, these methods are limited by high pumping pressure, susceptibility to mechanical failure, and lack of adaptability. A relatively new method of cooling that is the focus of this paper is Digitized Heat Transfer (DHT) [11–13], a method that has the potential to provide a reliable, highly adaptable, and efficient thermal management solution.

DHT is a method of thermal management that utilizes discrete microdroplets translating across heated surfaces to remove excess heat. Several methods of droplet transport have been proposed including dielectrophoresis [14], acoustic waves [15] thermocapillarity [16], and electrowetting [17,18]. Among these methods, Electrowetting On a Dielectric (EWOD) has become the most popular due to its low energy consumption, high actuation velocities, and programmability. EWOD uses electrodes beneath a dielectric layer to manipulate droplet wetting behavior. On an array of electrodes, voltage can be applied such that the electrode beneath the leading edge of the droplet is always activated. This in turn will cause droplet motion in the direction of the activated electrode. One of the primary advantages of this method is its mechanical simplicity. The system does not require any pumps or valves, thus creating a system that is less prone to failure. Furthermore, droplet paths are fully programmable and can be reconfigured by simply editing a computer program. This allows for real time droplet path optimization for changing temperature distributions. Fig. 1 shows a conceptual representation of a simple DHT device that could transport discrete droplets using any of the methods mentioned previously. As seen in the theoretical device, droplets can be transported across the heated surface along hundreds of different paths, creating a flexible

and adaptable system. While electrodes are patterned directly onto the heated surface in Fig. 1, an alternative configuration could pattern electrodes on a separate plate that is placed opposing the heated surface. Coolant would flow between the heated surface and the actuation plate, thus creating a more modular system. In terms of heat transfer, digitized flows have shown higher heat transfer rates than continuous flows with equivalent mass flow rates [12,13]. While heat transfer to digitized flow has been studied previously [12,13,19–25], most of these studies have been limited to specific Reynolds numbers, Prandtl numbers, and aspect ratios. Amongst these studies, multiple parameters were simultaneously

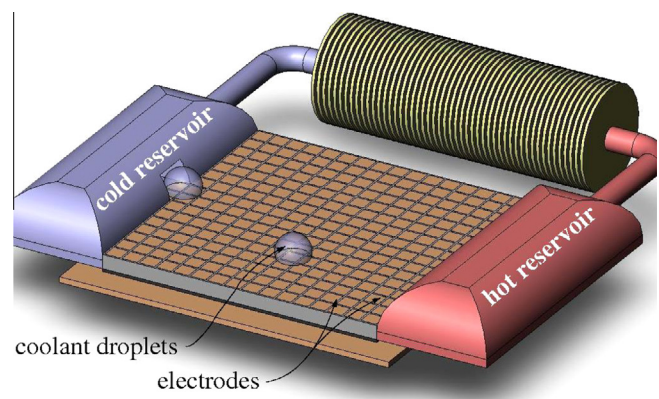


Fig. 1. DHT concept device.

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